



ey Docket Number: 5298-03500

PM99021

DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address, and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled "METHOD FOR FORMING A METALLIZATION STRUCTURE IN AN INTEGRATED CIRCUIT," the specification of which:

is attached hereto. was filed on and was amended on		plication Serial No (if applicable).	
I hereby state that I have r including the claims, as amended by a		stand the contents of the above dto above.	ove-identified specification,
I acknowledge the duty to di material to patentability of the subject 1.56.		and Trademark Office all info	
I hereby claim foreign price application(s) for patent or inventor's clisted below designating least one conforeign application for patent or inventore that of the application on which	certificate listed belo intry other than the later or control of the later of the l	United States of America, and	CT international application d have identified below any
Prior Foreign Application No.	Country	Filing Date (mm/dd/yy)	Priority Cert. copy Claimed Attached
N/A			
I hereby claim the benefit unbelow.	nder 35 U.S.C. § 119	e(e) of any United States prov	risional application(s) listed
Provisional Application No.	Filing Date (mm/dd/yy)		
N/A			
I hereby claim the benefit une § 365(c) of any PCT international app the subject matter of each of the clainternational application in the manner disclose all information known to mapplication, as "materiality" is defined prior application and the national or PC	lication listed below sims of this applicate provided by the first to be material to d in 37 C.F.R. § 1.50 CT international filin	designating the United States ion is not disclosed in the pt paragraph of 35 U.S.C. § 112 the patentability of the sub 5, which became available be g date of this application.	of America, and, insofar as prior United States or PCT 2, I acknowledge the duty to ject matter claimed in this tween the filing date of the
Parent Application No.	Filing Date (mm/dd/yy)	Parent Patent No. (if a	ipplicable) or Status
N/A			



The Assignee hereby revokes any previous Powers of Attorney and appoints Andrew D. Fortney, Reg. No. 34,600 of Cypress Semiconductor Corporation, and Kevin L. Daffer, Reg. No. 34,146; B. Noel Kivlin, Reg. No. 33,929; and, Eric B. Meyertons, Reg. No. 34,876 of the firm of Conley, Rose & Tayon, as attorney or agent for so long as they remain with such company or firm, with full power of substitution and revocation, to prosecute the application, to make alterations and amendments therein, to transact all business in the Patent and Trademark Office in connection therewith, and to receive the Letters Patent.

Please direct all communications to:

Kevin L. Daffer Conley, Rose & Tayon, P.C. P.O. Box 398 Austin, Texas 78767-0398 Phone: (512) 476-1400

I hereby declare that all statements made herein of my own knowledge are true and that all statements made herein on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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